

MULTI FUNCTION PACKAGE**Abstract of the Disclosure**

5 A multi-chip package for a computer disc drive. In a preferred
embodiment, the multi-chip package (MCP) includes a first die having a
buffer function thereon, such as an SDRAM device, and a second die
including a channel function and a controller function thereon. The two die
are packaged in a single package for placement on a printed circuit board
10 of the disc drive.